

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
 Organization
 International Bureau



(43) International Publication Date
 18 March 2004 (18.03.2004)

PCT

(10) International Publication Number
WO 2004/022814 A2

(51) International Patent Classification⁷: **C23C 18/00**

(21) International Application Number:
 PCT/EP2003/009526

(22) International Filing Date: 28 August 2003 (28.08.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
 102 41 619.2 4 September 2002 (04.09.2002) DE

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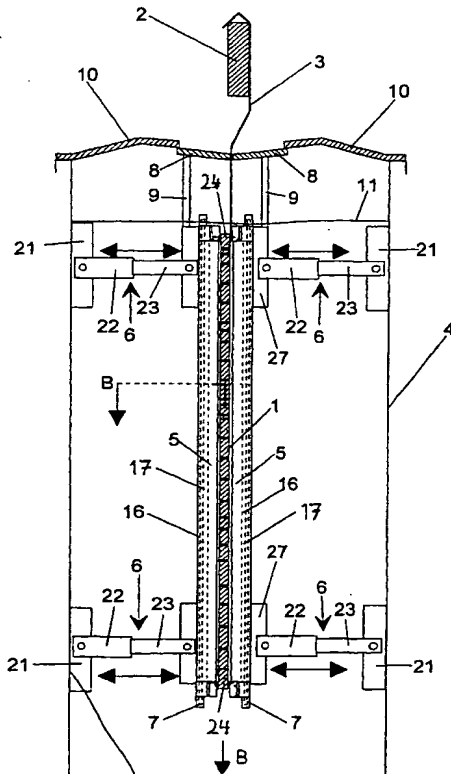
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(81) Designated States (national): AE, AG, AL, AM, AT, AU,
 AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU,
 CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH,
 GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC,
 LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW,
 MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC,
 SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA,
 UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (regional): ARIPO patent (GH, GM,
 KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW),

[Continued on next page]

(54) Title: DEVICE AND METHOD FOR ELECTROLYTICALLY TREATING AN AT LEAST SUPERFICIALLY ELECTRICALLY CONDUCTING WORK PIECE



(57) Abstract: A problem during electrolytic treatment of printed circuit boards having a very thin basic metallization is that the treatment yields irregular results in various regions on the surface of the printed circuit board. In overcoming this problem the invention provides a device for electrolytically treating an at least superficially electrically conducting work piece having at least two substantially opposing side edges. The device comprises current supply devices for the work piece, said current supply devices each comprising contact strips located on the opposing side edges which are capable of electrically contacting the work piece at the substantially opposing side edges.

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